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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

|                           |   |                  |                     |
|---------------------------|---|------------------|---------------------|
| Appl. No.                 | 10/813,407  | Confirmation No. | 5642                |
| First Inventor            | Jiping Li   | Filing Date      | March 29, 2004      |
| Tech. Center/<br>Art Unit | 2822  | Examiner         | Trinh, Michael Manh |
| Title:                    | High Throughput Measurement Of Via Defects In Interconnects |                  |                     |
| Docket No.:               | 008546USA   | Customer No.:    | 34036               |

Santa Clara, California  
December 20, 2005

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**AMENDMENT AFTER NOTICE OF ALLOWANCE**

**UNDER 37 C.F.R. 1.312**

Dear Sir:

In response to Notice of Allowance dated April 27, 2005, please amend the above-identified application as follows.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Drawings** begin on page 3 of this paper and include two replacement sheets.

**Remarks/Arguments** begin on page 4 of this paper.

An **Appendix** including two replacement drawing figures (and a cover sheet) is attached following page 4 of this paper.